

2020 Applied Materials Technical Symposium in Korea

The AI Landscape: Semiconductors and Computing Architectures

February 7, COEX Seoul, 3F, Room 318

Time	Title	Presenter
11:45 - 13:00	Registration / Lunch	
13:00 - 13:10	Welcome	
13:10 - 13:45	Modeling of Reliability and Variability in 3D NAND Flash Memory	Hyungcheol Shin, Seoul National University
13:45 - 14:10	Challenges and Solutions to Interconnect Scaling	Kevin Moraes, Applied Materials
14:10 - 14:25	Break	
14:25 - 15:00	Evolution of CMOS Image Sensor Pixel – Technical Challenges and Innovations	Hoon Sang Oh, SK hynix
15:00 - 15:25	A New Focus on a Fast Growing Market	Werner Finsterbusch, Applied Materials
15:25 - 16:00	3D NAND Challenges and Opportunities	Tae Kyung Kim, Intel
16:00 - 16:05	Conclusion	